



SPECIFICATION

Customer : _____

Customer P/N : **OS70504A-AQAN-25.60MHz**

Agent : _____

Agent Code : _____

Order Code : _____

P/N : _____

Customer Approval :

东莞市大普通信技术有限公司

Dongguan DAPU Telecom Technology co.,Ltd

市场/SALE DEPARTMENT

TEL: 0769-81867888

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URL [HTTP://www.dptel.com](http://www.dptel.com)

Date : _____

Approved By: _____

品质部/QUALITY ASSURANCE DEPT

TEL:0769-81867888-833

Checked By: _____

研发部/R&D DEPT.

TEL:0769-81867888-828

Designer : _____



1、 Scope:

- | | | |
|-----|-------------------------|------------------------|
| 1.1 | Description: | SMD Crystal Oscillator |
| 1.2 | Center Frequency: | 25.60MHz |
| 1.3 | Dimension & Drawing No: | OS70504A-AQAN-25.60MHz |

2、 Construction:

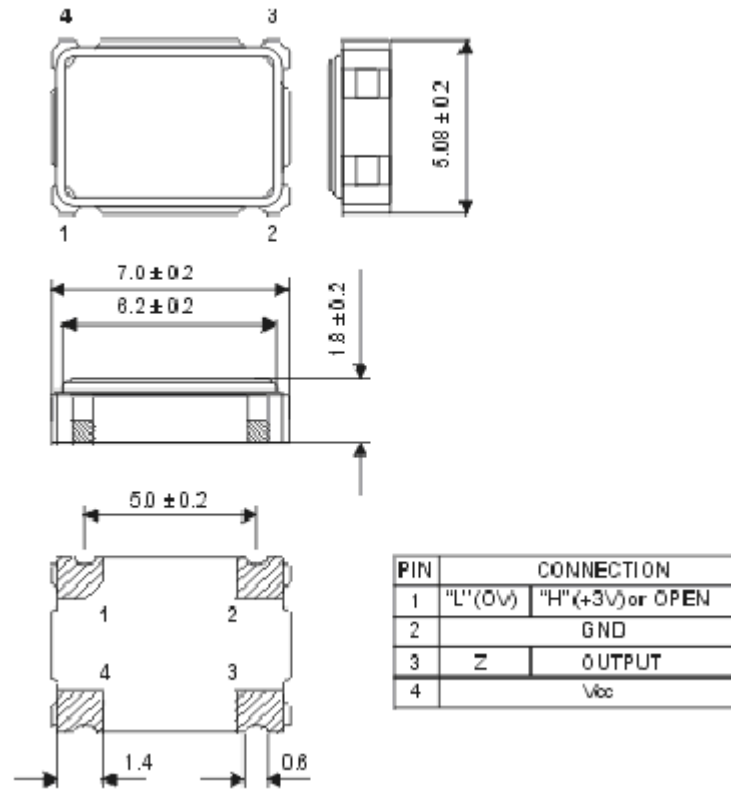
- 2.1 Oscillators series: SMD7×5 XO

3、 Electrical Characteristics

- | | | |
|------|------------------------------|---|
| 3.1 | Nominal Frequency: | 25.60MHz |
| 3.2 | Frequency Tolerance: | $\leq \pm 20\text{ppm}$ @ at 25°C $\pm 3^\circ\text{C}$ |
| 3.3 | Aging: | $\leq \pm 2\text{ppm}/\text{first year}$ |
| 3.4 | Temperature Tolerance | $\leq \pm 40\text{ppm}$ |
| 3.5 | Operating Temperature Range: | -40°C to +85°C |
| 3.6 | Storage Temperature Range: | -55°C to +125°C |
| 3.7 | Input Voltage: | +3.3VDC $\pm 5\%$ |
| 3.8 | Current Consumption: | 22mA Max |
| 3.9 | Output Waveform: | Clipped Sine Wave , 0.8Vp-p min |
| 3.10 | Load | 10k Ω //10pF |
| 3.11 | Start up Time: | $\leq 10\text{ms}$ |
| 3.12 | Rating empty | 50% $\pm 10\%$ |
| 3.13 | Symmetry | 50% $\pm 10\%$ at 1/2Vcc level |
| 3.14 | Enable/Disable time | 100ns Max |
| 3.15 | Reflow soldering cond. | 10 seconds Max at 240°C |



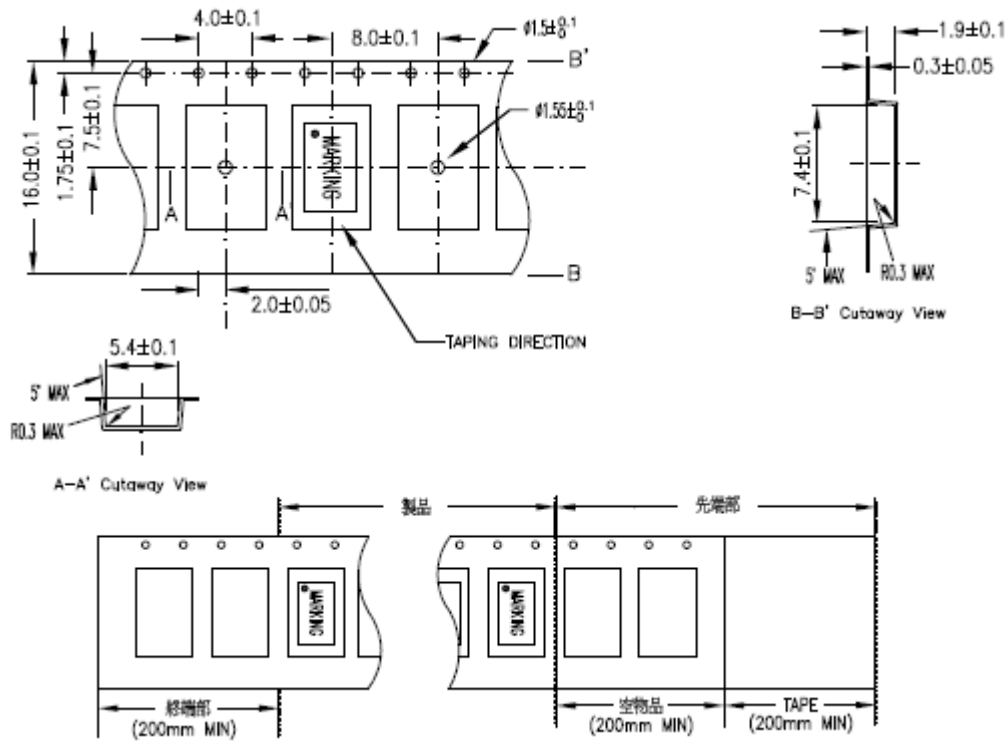
4. Figure



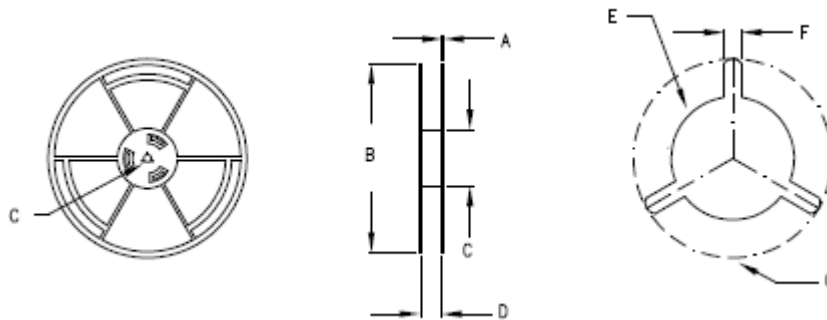
Unit : mm



5. Carrier Type



6. Reel



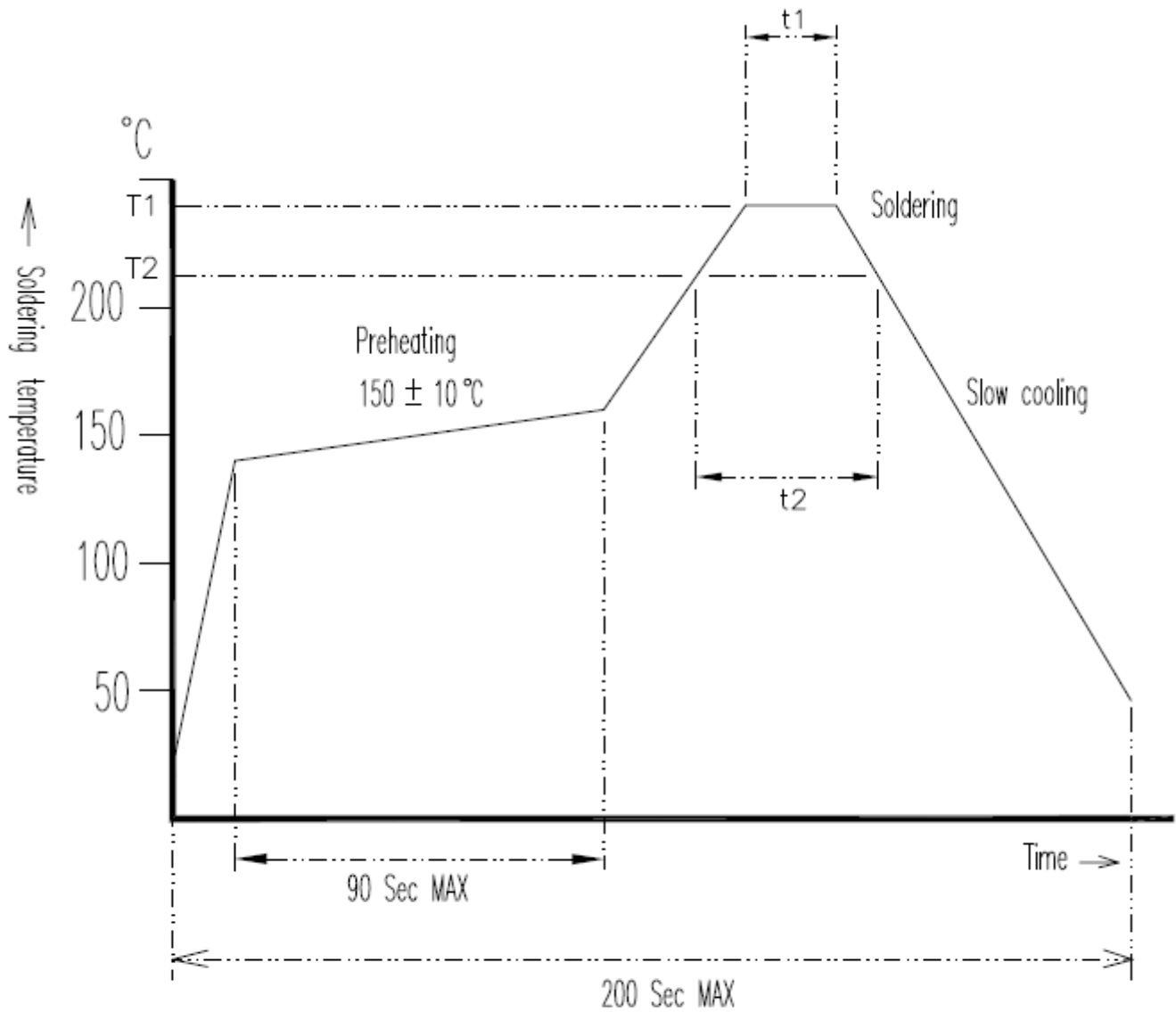


7. Environmental Performance

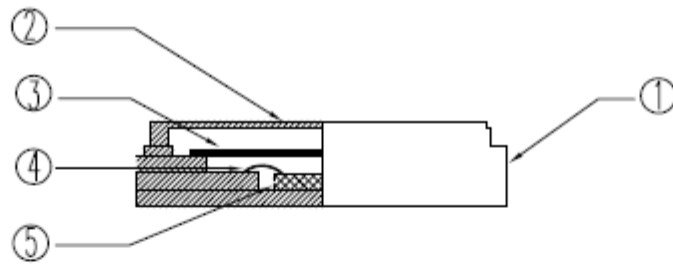
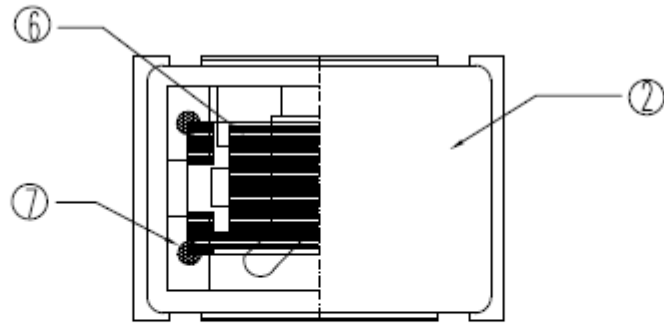
ITEM	CONDITION	SPECIFICATIONS					
1. Low temperature storage	Temp. : -40 ±3°C Time : 1000 ±2 H Measure after leaving a room for 1~2 H	Frequency stability ΔF : ± 5.0 ppm max					
2. High temperature storage	Temp. : +85 ±2°C Time : 1000 ±2 H Measure after leaving a room for 1~2 H						
3. Moisture resistance (High temperature and highhumidity storage)	Temp. : +85 ±2°C Hum. : 90 ~ 95%RH Time : 1000 ±2 H Measure after leaving a room for 2 hours						
4. Shock	A half sine wave acceleration of 490 m/s ² peak amplitude of 7 to 11 ms duration 3 shock each plane.						
5. Damp heat cycle	Setup temperature and test time as below table : Cycle : 100 cycles Measure after leaving a room for 2 hour <table border="1" style="margin-left: 20px;"> <thead> <tr> <th>Temperature</th> <th>Time</th> </tr> </thead> <tbody> <tr> <td>Operating Temp. (Low Temp.) +0/-6°C</td> <td>30 ± 3 min</td> </tr> <tr> <td>Operating Temp. (High Temp.) +4/-0°C</td> <td>30 ± 3 min</td> </tr> </tbody> </table>		Temperature	Time	Operating Temp. (Low Temp.) +0/-6°C	30 ± 3 min	Operating Temp. (High Temp.) +4/-0°C
Temperature	Time						
Operating Temp. (Low Temp.) +0/-6°C	30 ± 3 min						
Operating Temp. (High Temp.) +4/-0°C	30 ± 3 min						

8. Mechanical Performance

6. Solderability	Solder bath : +235°C ±5°C Time: 2 ±0.5 S	The dipping surface of the lead shall be at least 95% covered with a continuous new solder coating.
7. Resistance to soldering heat	Solder bath : +260°C ±5°C Time: 2 ±0.5 S Reflow chart as attach sheet. (2 Times)	<ul style="list-style-type: none"> • Shall Be free from any defectiveness on its surface. • Frequency stability ΔF : ±5.0 ppm max
8. Airtight	Solder bath : +260°C ±5°C Time: 2 ±0.5 S Reflow chart as attach sheet. (2 Times)	Less than 1x1E-8 mbarL/S.
9. Vibration	Frequency : 10 ~ 55Hz, amplitude (total excursion): 1.5mm±15%, 3 Direction (X, Y, Z) each 2 H.	Frequency stability ΔF : ±5.0 ppm max
10. Shock	Dropping form 75 cm high 2 times on hard wood.	Same as above.



Application \ Temperature/Time	T_1/t_1	T_2/t_2
Lead Free	$260 \pm 5^{\circ}\text{C}/10 \text{ Sec Max}$	$225^{\circ}\text{C Min}/60 \text{ Sec Max}$
Non Lead Free	$240 \pm 5^{\circ}\text{C}/10 \text{ Sec Max}$	$200^{\circ}\text{C Min}/40 \text{ Sec Max}$



PART NAME	MATERIAL	PART NAME	MATERIAL	PART NAME	MATERIAL			
1	BASE	CERAMIC	4	WIRE	ALUMINIUM	7	ADHESIVES	SILVER GLUE
2	CAP	CERAMIC	5	IC	Si			
3	BLANK	QUARTZ	6	ELECTRODE	Cr+Ag			